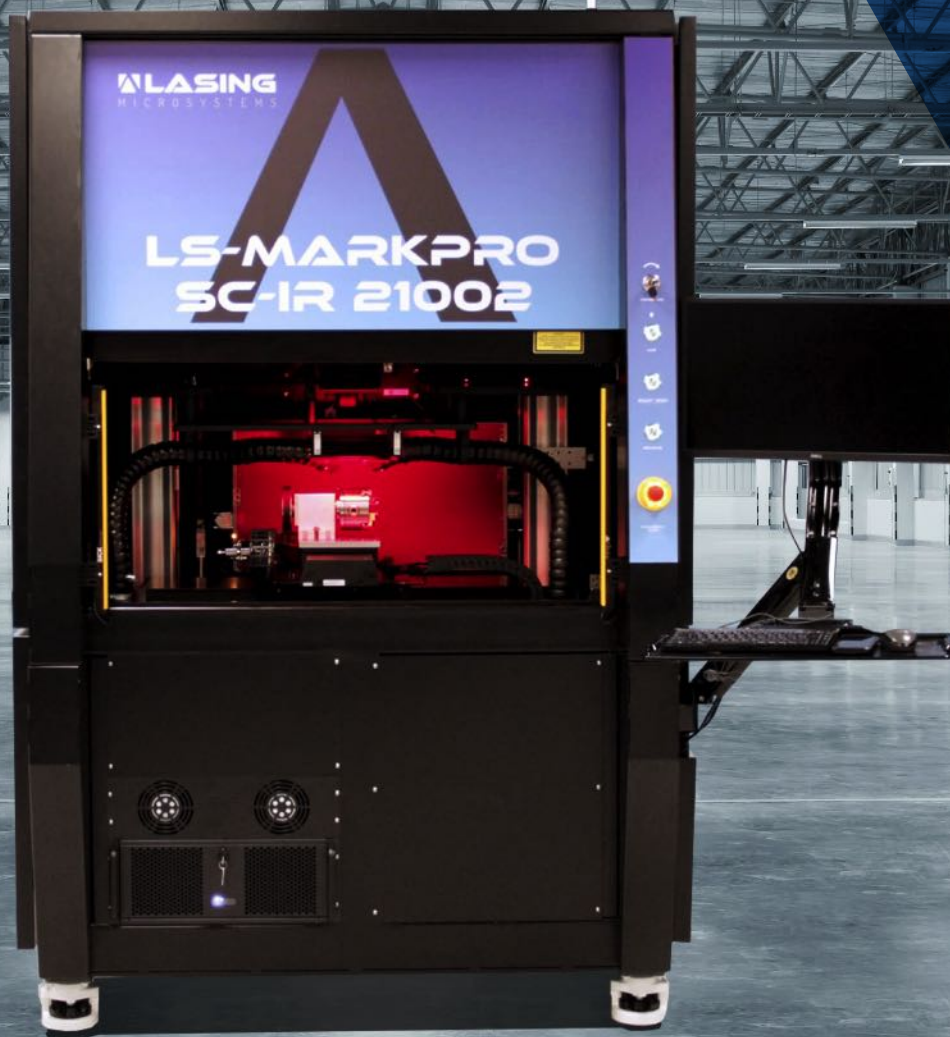
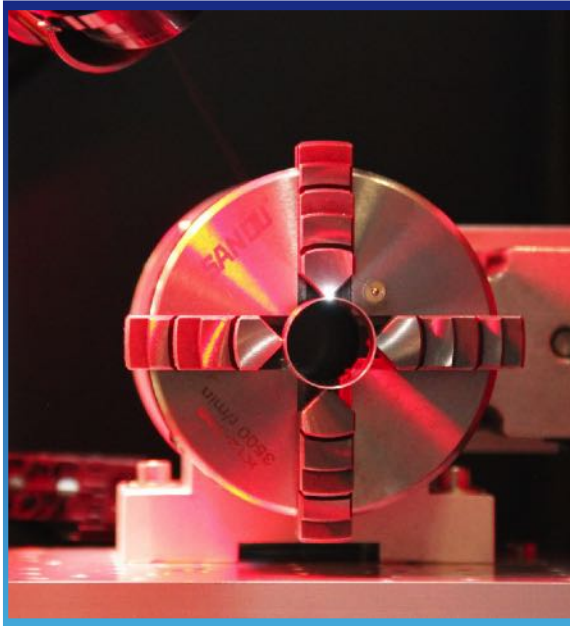


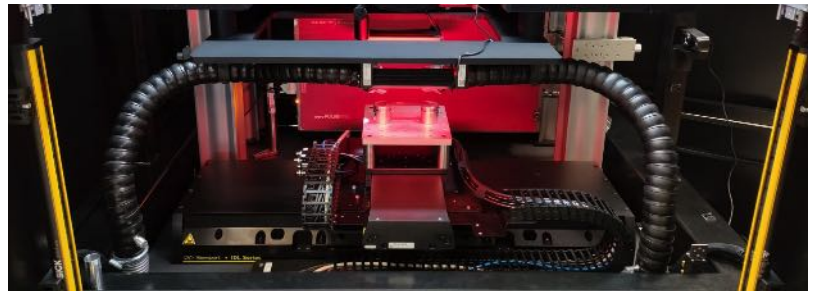
LS-MARKPRO



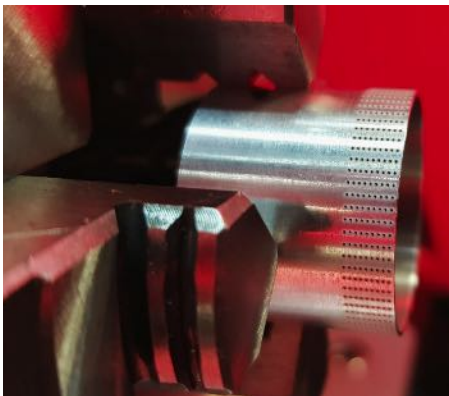
CUSTOMIZABLE LASER PROCESSING MACHINE FOR MARKING & ENGRAVING



LS-MARKPRO is a versatile workstation designed for high demanding laser processing applications where nanometer resolutions and laser spot sizes down to 1 micron are required. The main heavy granite structure with passive dampers and advanced solutions like close loop surface measurement for automatic focus correction, provides extremely high accuracy and stability even for complex trajectories. User friendly software with CAD GUI environment (codeless programming) ensures an efficient and fast process development.



STANDARD SPECIFICATIONS



Working Area	Up to 500 mm x 300 mm x 150 mm
Resolution	10 nm (XY), 0.3 μm (Z)
Repeatability	$< \pm 40$ nm (XY); ± 0.5 μm (Z)
Accuracy	± 2.5 μm (XY); ± 2.5 μm (Z)
Available Laser Sources	From UV to IR. Pulsed or CW
Substrate Holder	250 x 200 mm Aluminium Vacuum Plate
Minimum Laser Spot Size	Typical from 1 μm
External Dimensions	1400 mm x 1500 mm x 2200 mm (WxDxH)
Weight	1700 Kg without laser source
Control Unit	Workstation with dual 23" monitor

FEATURES:

- Femtosecond laser compatible.
- 2D precise galvanometer head with integrated Through The Lens vision system.
- High precision XYZ servo positioners.
- Up to 5 interpolated Axis.
- Advanced software for easy and intuitive object design.
- Robust granite based design or stainless-steel honeycomb table with passive dampers.*
- Class 1 enclosure.

* Depending on application and weight limitations.

OPTIONS:

- Advance nanometer surface analysis can be implemented with confocal and interferometric techniques making LS-MARKPRO a complete solution for laser processing services.
- Multiple laser sources with automatic path alignment.
- Multiple fixed processing head with different magnifications.
- 4th Axis (rotation stage) interpolated with XYZ.
- Compact cutting table with pneumatic holders.
- Fume exhaust extractor with EPA filter.
- Additional options.